

ABSTRACT OF THE DISCLOSURE

POLISHING APPARATUS

5 There is disclosed a polishing apparatus which can regulate a surface temperature of the polishing pad without causing a defect such as a scratch on a substrate such as a wafer. The polishing apparatus includes: a non-contact type pad-temperature regulating device; a pad-temperature measuring device. The pad-temperature measuring device is arranged adjacent to the pad-temperature regulating device and on a downstream side of the pad-
10 temperature regulating device in a rotation direction of a polishing table.

FIG. 1